## **GIGABYTE**<sup>™</sup>

# G593-ZD1-AAX3

### HPC/AI Server - 5U DP NVIDIA HGX<sup>™</sup> H200 8-GPU







#### **Features**

- 5U server system with NVIDIA HGX<sup>™</sup> H200 8-GPU
- 900GB/s GPU-to-GPU bandwidth with NVLink<sup>®</sup> and NVSwitch<sup>™</sup>
- Dual AMD EPYC<sup>™</sup> 9004 Series Processors
- 12-Channel RDIMM DDR5, 24 x DIMMs
- Dual ROM Architecture
- 2 x 10Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen3 x4 and x1 interface
- 8 x 2.5" Gen5 NVMe hot-swappable bays
- 4 x FHHL PCIe Gen5 x16 slots
- 8 x LP PCIe Gen5 x16 slots
- 4+2 3000W 80 PLUS Titanium redundant power supplies

#### Application

#### AI, AI Inference, AI Training, High-Performance Computing

#### Specification

Dimensions	5U (W447 x H219.7 x D945 mm)	ТРМ	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
Motherboard	MZB3-G43	Backplane Board	Speed and bandwidth: PCle Gen5 x4 or SATA 6Gb/s or SAS-4 24Gb/s
CPU	AMD EPYC <sup>™</sup> 9004 Series processors AMD EPYC <sup>™</sup> 9004 Series processors with AMD 3D V-Cache <sup>™</sup> Dual processor, 5nm technology (LGA 6096 Socket SP5) cTDP up to 300W at ambient 35°C	Power Supply	4+2 3000W 80 PLUS Titanium redundant power supply AC Input: 115-240V *The system power supply requires C19 power cord.
Chipset	System on Chip	System Management	ASPEED® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
Memory	24 x DIMM slots, 12-Channel DDR5 memory RDIMM modules up to 96GB supported 3DS RDIMM modules up to 256GB supported Memory speed: Up to 4800 MT/s	OS Compatibility	Windows Server, Red Hat Enterprise Linux Server, VMware ESXi, SUSE Linux Enterprise, Ubuntu Server, Citrix Hypervisor
LAN	2 x 10Gb/s LAN ports (1 x Intel® X710-AT2) - Support NCSI function 1 x 10/100/1000 management LAN	System Fans	2 x 40x40x56mm (32,000rpm), 4 x 60x60x56mm (24,000rpm), 4 x 40x40x28mm (25,000rpm), 2 x 40x40x56mm (32,000rpm) 6 x 60x60x76mm (21,700rpm), 11 x 80x80x80mm (17,000rpm)
Video	Integrated in ASPEED® AST2600 - 1 x VGA port	Operating Properties Packaging Content	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Storage	8 x 2.5" Gen5 NVMe/SATA/SAS-4 hot-swappable bays *Storage card is required to support SATA and SAS drives.		
	1 x M.2 slot: M-key, PCIe Gen3 x4, supports 2280/22110 cards 1 x M.2 slot: M-key, PCIe Gen3 x1, supports 2280/22110 cards		1 x G593-ZD1-AAX3, 2 x CPU heatsinks, 1 x L-shape Rail kit Packaging Dimensions: 1200 x 890 x 700 mm
Expansion Slots	NVIDIA HGX™ H200 with 8 x SXM5 GPUs (8-root ports) 8 x PCIe Gen5 x16 low-profile slots 4 x PCIe Gen5 x16 FHHL slots	Part Numbers	Barebone w/ NVIDIA module: 6NG593ZD1DR000AAX3* - L-shape Rai kit: 25HB2-A96102-K0R - CPU heatsink: 25ST1-44320Z-C1R - Power supply: 25EP0-23000J-D0S - C19 power cord 125V/15A (US): 25CP1-018000-Q0R (optional) - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional) - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R (optional)
I/O ports	Front: 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) Rear: 1 x MLAN Internal: 1 x TPM header		



#### Learn more at https://www.GIGABYTE.com/enterprise

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